

**30V P-Channel Enhancement Mode MOSFET****Description**

The PECN3401HR uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

**General Features**

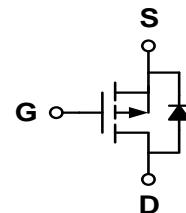
- ◆  $V_{DS} = -30V$ ,  $I_D = -4A$   
 $R_{DS(ON)}(\text{Typ.}) = 57m\Omega$  @  $V_{GS} = -4.5V$   
 $R_{DS(ON)}(\text{Typ.}) = 87m\Omega$  @  $V_{GS} = -2.5V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

**Application**

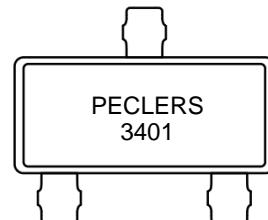
- ◆ PWM applications
- ◆ Load switch

**Package**

- ◆ ESOT-23-3L

**Schematic diagram****Marking and pin assignment**

ESOT-23  
(TOP VIEW)

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN3401HR	-55°C to +150°C	ESOT-23-3L	5000

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	-30	V
Gate-source voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	-4	A
		-3.0	
Pulsed Drain Current <sup>C</sup>	$I_{DP}$	-16	A
power dissipation <sup>B</sup>	$P_D$	1.4	W
		0.9	

Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>SGT</sub>	-55—150	°C
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**Electrical Characteristics** (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-30	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V	-	-	±100	nA
<b>ON Characteristics</b>						
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.6	-0.8	-1.3	V
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	57	60	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A	-	87	100	
Forward transconductance	G <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-4A	-	5	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V f=1.0MHz	-	456	-	pF
Output capacitance	C <sub>OSS</sub>		-	64	-	
Reverse transfer capacitance	C <sub>RSS</sub>		-	57	-	
Gate resistance	R <sub>g</sub>	V <sub>DS</sub> =15mV, f=1.0MHz	-	10	-	Ω
<b>Switching Characteristics</b>						
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>DS</sub> =-15V I <sub>D</sub> =-4A V <sub>GEN</sub> =-10V R <sub>L</sub> =10ohm R <sub>GEN</sub> =6ohm	-	3.0	3.5	ns
Rise time	tr		-	31	35	
Turn-off delay time	t <sub>D(OFF)</sub>		-	33	40	
Fall time	tf		-	8	12	
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V, I <sub>D</sub> =-4A V <sub>GS</sub> =-4.5V	-	13	-	nC
Gate-source charge	Q <sub>gs</sub>		-	1	-	
Gate-drain charge	Q <sub>gd</sub>		-	2.1	-	
Body Diode Reverse Recovery Time	trr	IF=-4A, dI/dt=100A/ms	-	24	-	nS
Body Diode Reverse Recovery Charge	Qrr	IF=-4A, dI/dt=100A/ms	-	1.8	-	nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =-4A	-	-0.81	-1.2	V

**Thermal Characteristics**

Parameter	Symbol	Typ.	Max.	Unit
Maximum Junction-to-Ambient <sup>A</sup>	t≤ 10s	R <sub>θJA</sub>	70	90
Maximum Junction-to-Ambient <sup>A D</sup>	Steady-State		100	125
Maximum Junction-to-Lead	Steady-State		62	80

A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design.

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- B. The power dissipation PD is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using  $\leq 10\text{s}$  junction-to-ambient thermal resistance.
  - C. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^{\circ}\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^{\circ}\text{C}$ .
  - D. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

### Typical Performance Characteristics

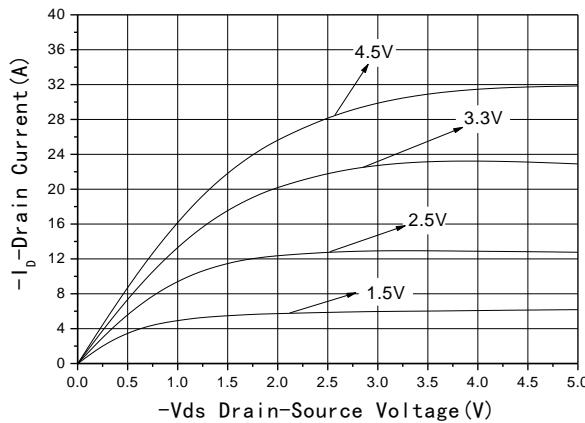


Fig1 Output Characteristics

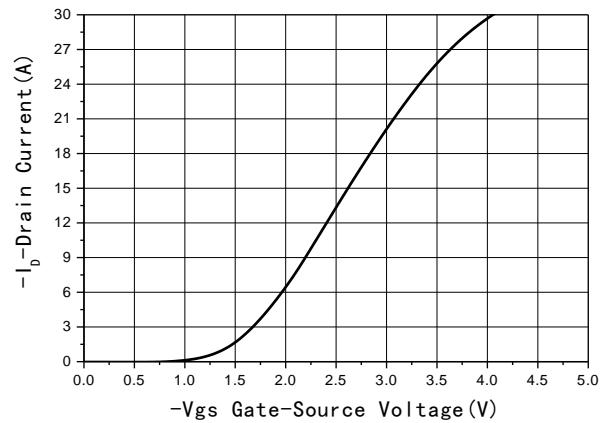


Fig2 Transfer Characteristics

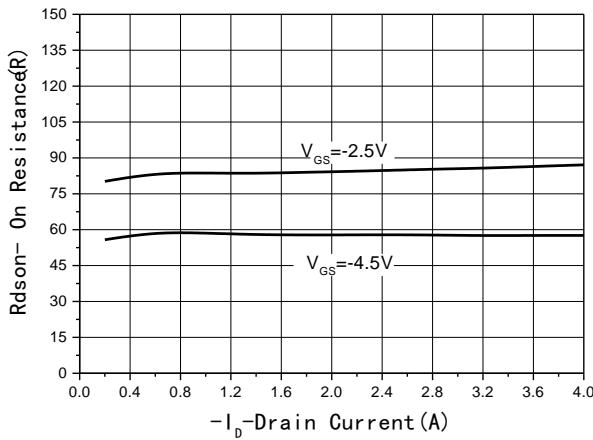


Fig3 Rdson-Drain current

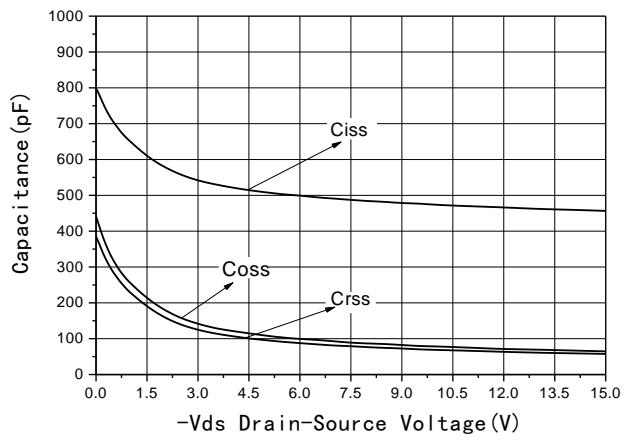


Fig4 Capacitance vs Vds

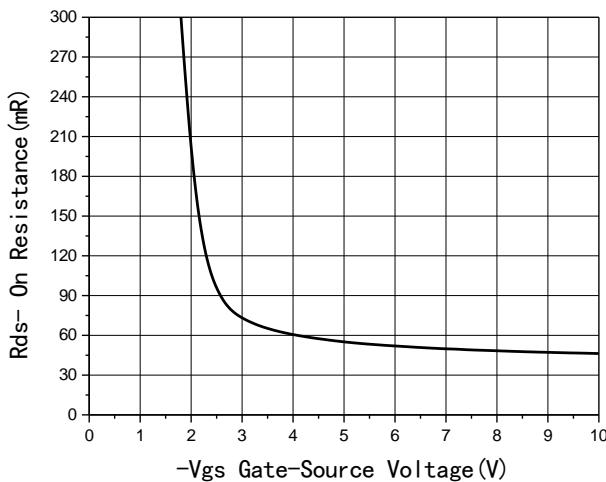


Fig5 Rdson-Gate voltage

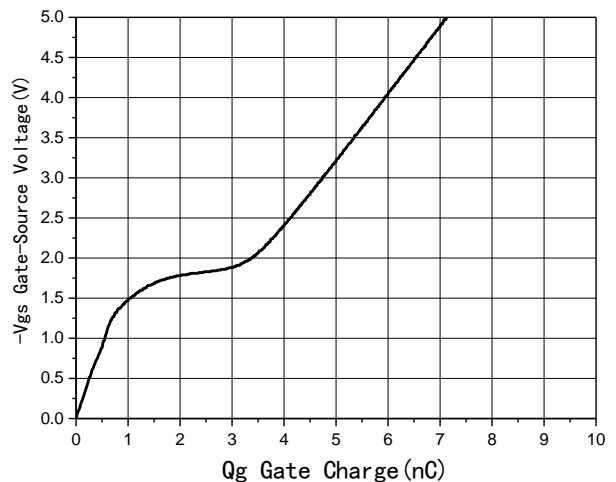
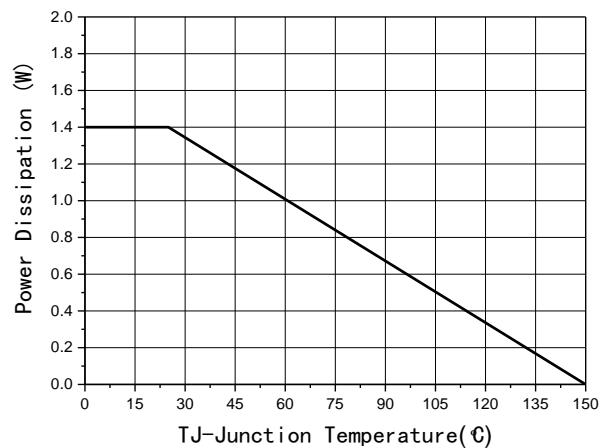
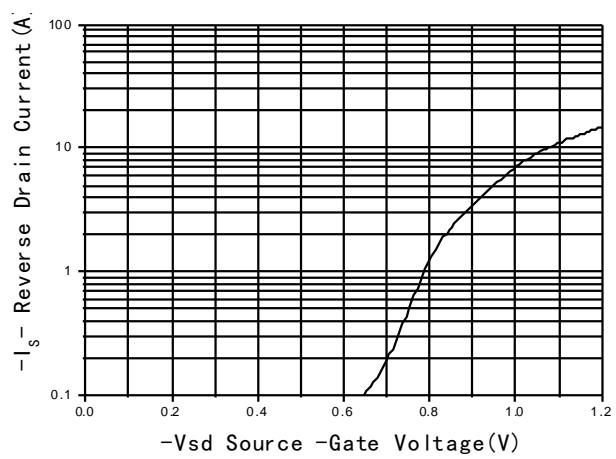


Fig6 Gate Charge



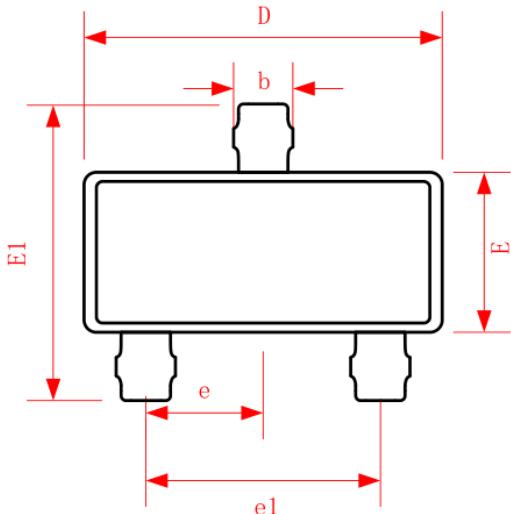
**Fig7 Power De-rating**



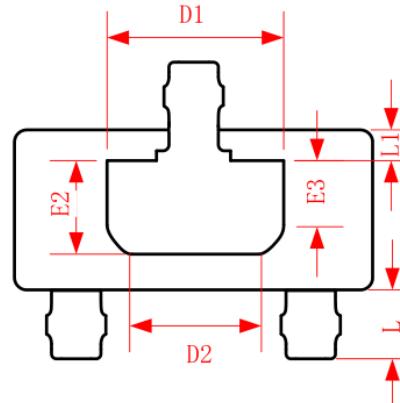
**Fig8 Source-Drain Diode Forward**

## Package Information

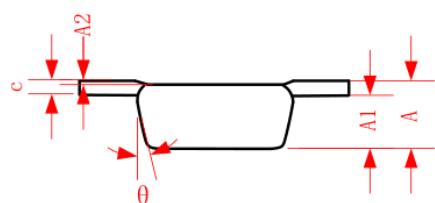
- ESOT-23



Top View  
【顶视图】



Bottom View  
【背视图】



Side View  
【侧视图】

Symbol	Dimensions In Millimeters		
	Min.	REF.	Max.
A	0.500	0.550	0.600
A1	0.368	0.398	0.428
A2	-0.030	0.000	0.030
c	0.152Ref		
D	2.850	2.900	2.950
E	1.250	1.300	1.350
E1	2.350	2.400	2.450
D1	1.405	1.430	1.455
D2	0.995	1.020	1.045
E2	0.735	0.760	0.785
E3	0.490	0.520	0.545
L	0.525	0.550	0.575
L1	0.235	0.260	0.285
e	0.950Ref		
e1	1.800	1.900	2.000
b	0.410	0.480	0.550
θ	14°	15°	16°